

**SURFACE MOUNT GENERAL RECTIFIER****Features**

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ Idea for printed circuit board
- ◆ Glass passivated junction
- ◆ Low reverse leakage
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed 250°C/10 seconds at terminals

**Mechanical Data**

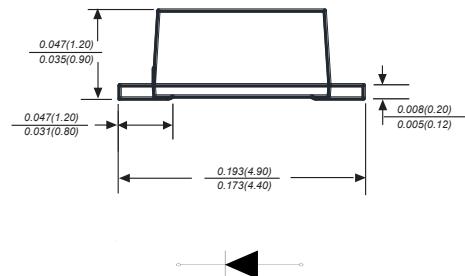
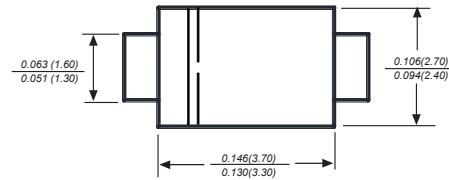
Case\*: JEDEC SMAF molded plastic body

Terminals\*: Solderable per MIL-STD-750, Method 2026

Polarity\*: Polarity symbol marking on body

Mounting Position\*: Any

Weight : 0.00095ounce, 0.027 grams

SMAF RoHS  
COMPLIANT

Dimensions in inches and (millimeters)

**Maximum Ratings And Electrical Characteristics**

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz,resistive or inductive load,for capacitive load current derate by 20%.

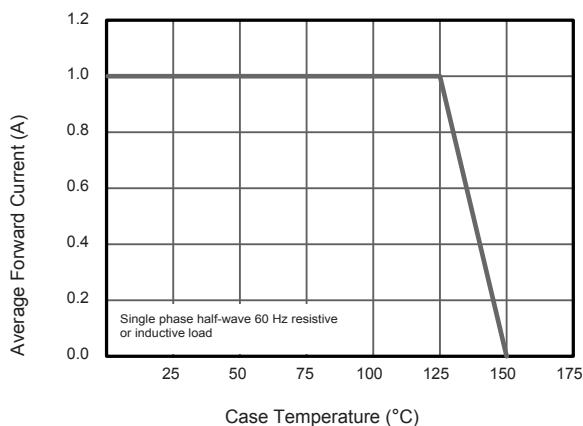
Parameter	SYMBOLS	MDD M1F	MDD M2F	MDD M3F	MDD M4F	MDD M5F	MDD M6F	MDD M7F	UNITS
Marking Code									
Maximum repetitive peak reverse voltage	$V_{RRM}$	50	100	200	400	600	800	1000	V
Maximum RMS voltage	$V_{RMS}$	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	$V_{DC}$	50	100	200	400	600	800	1000	V
Maximum average forward rectified current at $T_L=125^\circ C$	$I_{AV}$					1.0			A
Peak forward surge current 8.3ms single half sine-wave superimposed onrated load (JEDEC Method)	$I_{FSM}$					30			A
Maximum instantaneous forward voltage at 1.0A	$V_F$					1.10			V
Maximum DC reverse current $T_A=25^\circ C$ at rated DCblocking voltage $T_A=125^\circ C$	$I_R$					5.0			$\mu A$
						50.0			
Typical junction capacitance (NOTE 1)	$C_J$					15.0			pF
Typical thermal resistance (NOTE 2)	$R_{\theta JA}$					80.0			$^\circ C/W$
Operating junction and storage temperature range	$T_J, T_{STG}$					-55 to +150			$^\circ C$

Note:1.Measured at 1MHz and applied reverse voltage of 4.0V D.C.

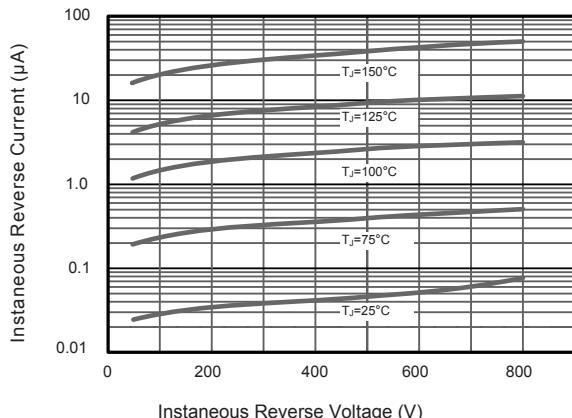
2.P.C.B. mounted with 2.0"x2.0"(5.0x5.0cm) copper pad areas

## Typical Characteristics

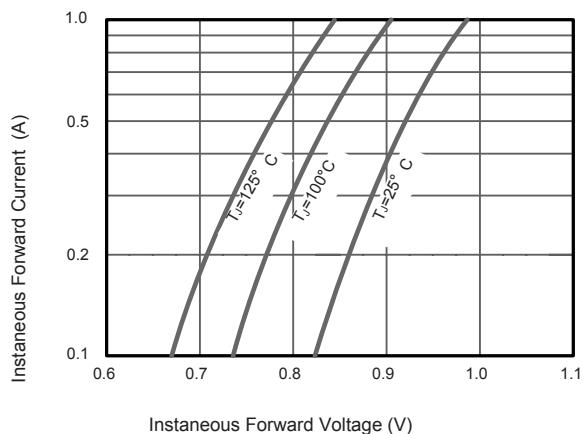
**Fig.1 Forward Current Derating Curve**



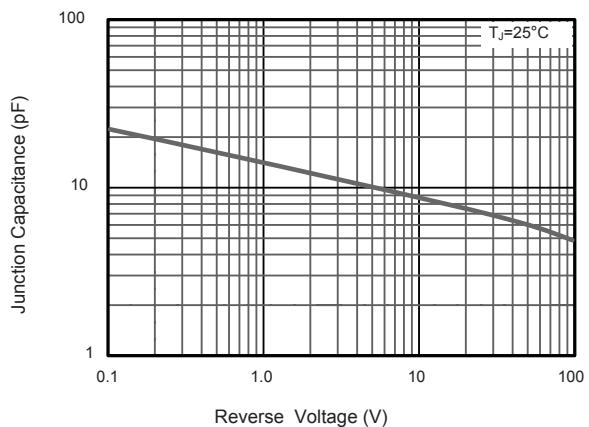
**Fig.2 Typical Instantaneous Reverse Characteristics**



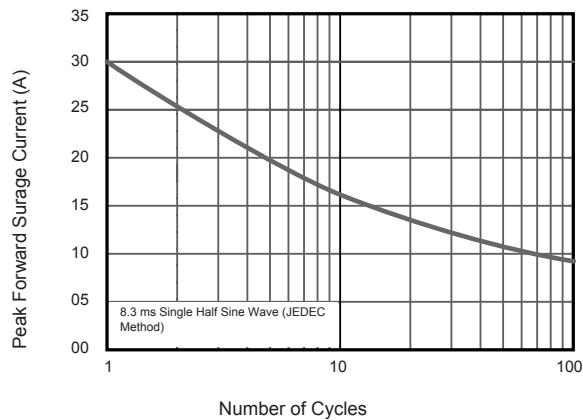
**Fig.3 Typical Forward Characteristic**



**Fig.4 Typical Junction Capacitance**

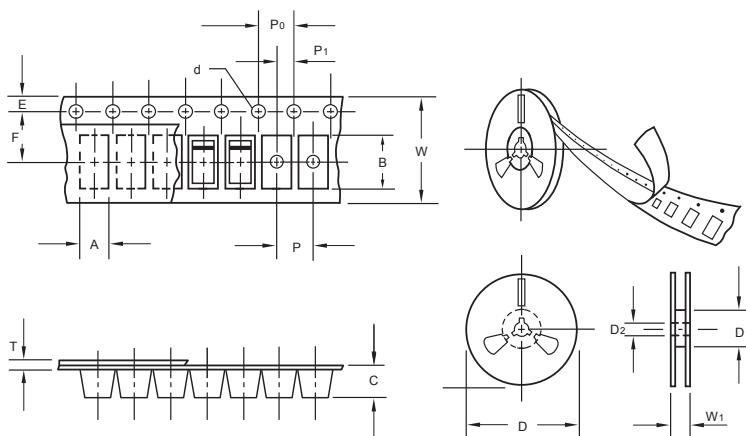


**Fig.5 Maximum Non-Repetitive Peak Forward Surge Current**



The curve above is for reference only.

## Packing information



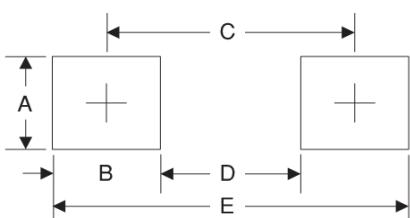
Item	Symbol	Tolerance	SMAF
Carrier width	A	0.1	2.80
Carrier length	B	0.1	4.75
Carrier depth	C	0.1	1.42
Sprocket hole	d	0.05	1.50
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D <sub>1</sub>	min	54.40
Feed hole diameter	D <sub>2</sub>	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	5.05
Punch hole pitch	P	0.1	4.00
Sprocket hole pitch	P <sub>0</sub>	0.1	4.00
Embossment center	P <sub>1</sub>	0.1	2.00
Overall tape thickness	T	0.1	0.30
Tape width	W	0.3	8.00
Reel width	W <sub>1</sub>	1.0	12.30

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

## Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SMAF	7"	3,000	4.0	6,000	210*208*203	178	400*265*400	120,000	10.0

## Suggested Pad Layout



Symbol	Unit (mm)	Unit (inch)
A	1.8	0.071
B	1.6	0.063
C	3.8	0.150
D	2.2	0.087
E	5.4	0.213